

USE OF VACUUM CHUCKS TO HOLD A WAFER OR WAFER SUB-STACK

ABSTRACT OF THE DISCLOSURE

Techniques are described for holding a wafer or wafer sub-stack to facilitate further processing of the wafer or sub-stack. In some implementations, a wafer or wafer sub-stack is held by a vacuum chuck in a manner that can help reduce bending of the wafer or wafer sub-stack.

Figure 5